



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



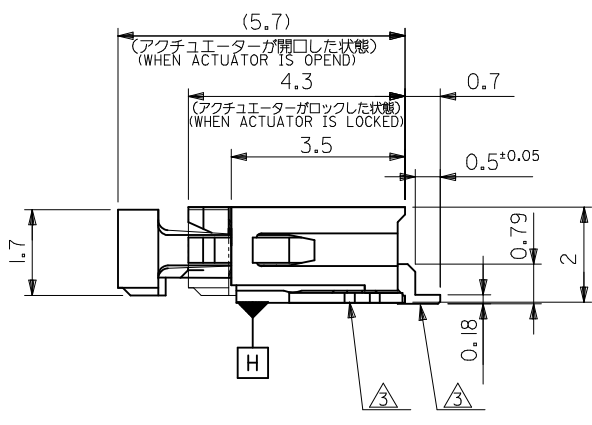
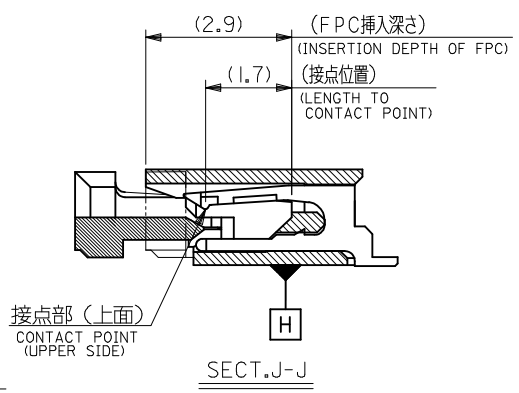
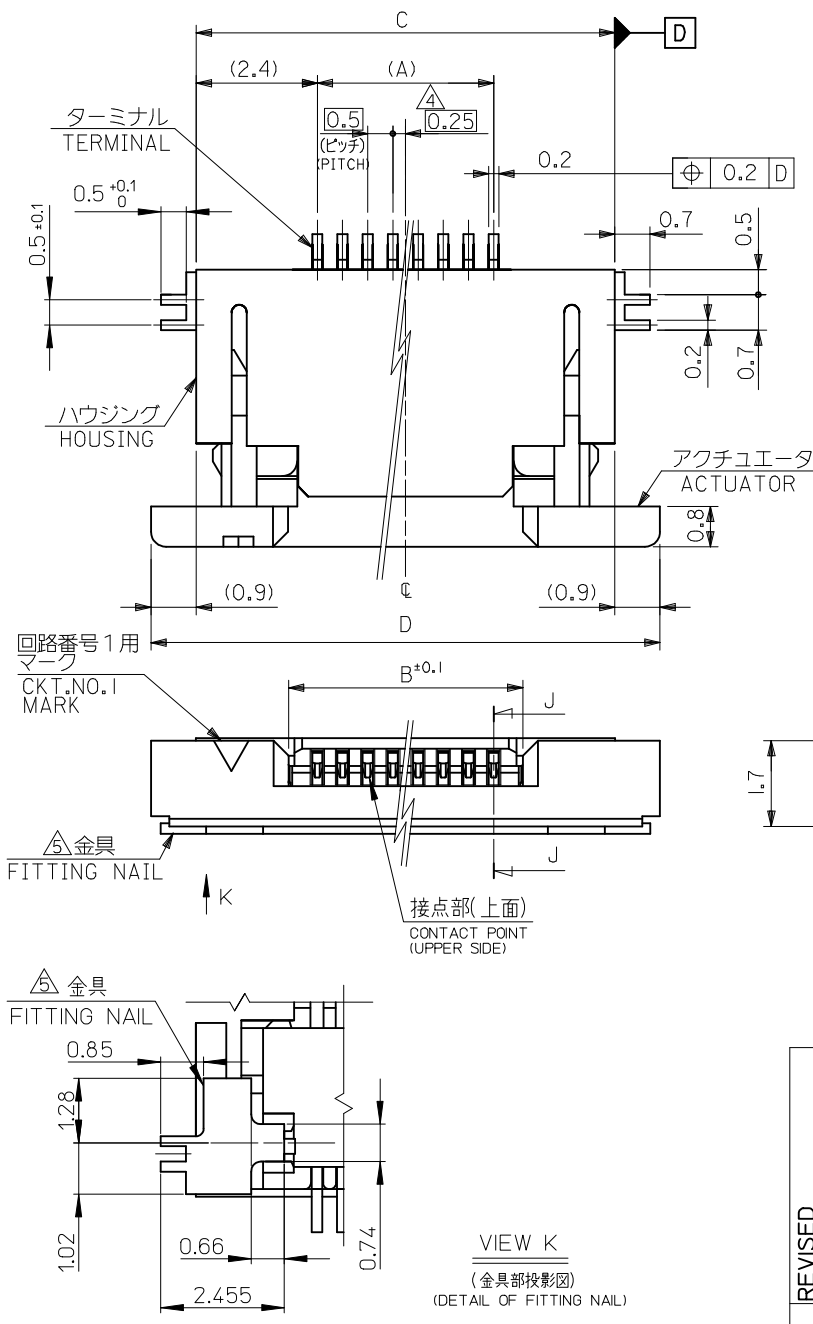
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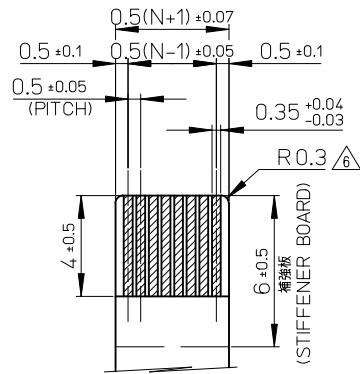




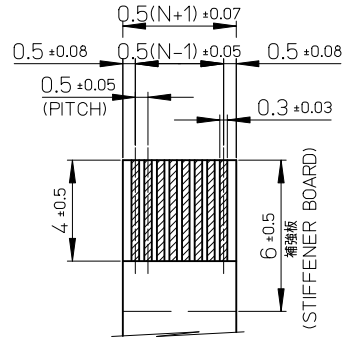
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14.6	12.8	9.15	8	52745-1797	17
14.1	12.3	8.65	7.5	52745-1697	16
13.6	11.8	8.15	7	52745-1597	15
13.1	11.3	7.65	6.5	52745-1497	14
12.6	10.8	7.15	6	52745-1397	13
12.1	10.3	6.65	5.5	52745-1297	12
11.6	9.8	6.15	5	52745-1197	11
11.1	9.3	5.65	4.5	52745-1097	10
10.6	8.8	5.15	4	52745-0997	9
10.1	8.3	4.65	3.5	52745-0897	8
9.6	7.8	4.15	3	52745-0797	7
9.1	7.3	3.65	2.5	52745-0697	6
8.1	6.3	2.65	1.5	52745-0497	4
D	C	B	(A)	EMBOSSED PACKAGE ORDER No. オーダー番号	極数 CKT.

CONNECTOR SERIES NO. : 52745-**59

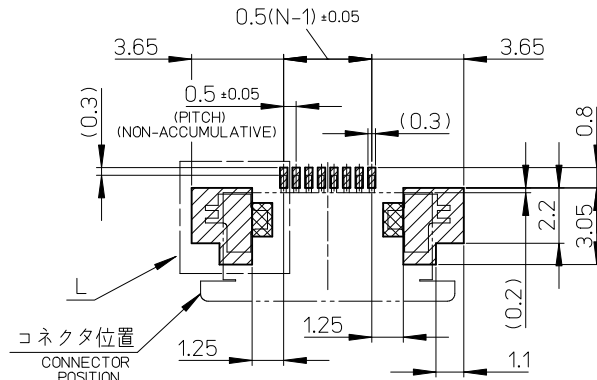
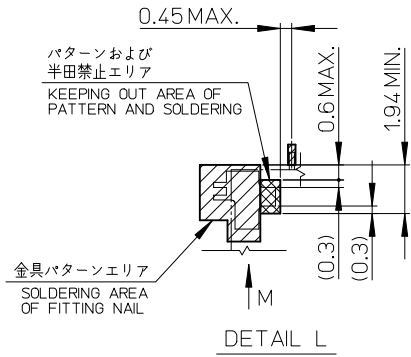
REVISED EC NO. J2011-0041 DRWN:HYOSHINO 2010/07/08 CHKD:HSHIMUYAMA 2010/07/08 APPR:KMORIKAWA 2010/07/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION		
	10 UNDER ±0.2		DRAWN BY M. NABE I		DATE '05/02/14		TITLE 0.5 FPC CONN. ZIF FOR SMT R/A (UPPER CONTACT) GOLD PLATING				
	10 OVER 30 UNDER ±0.25		CHECKED BY K. TOJO		DATE '05/02/14		MOLEX INCORPORATED				
	30 OVER ±0.3		APPROVED BY N. UKITA		DATE '05/02/14		DOCUMENT NO. SD-52745-050				
	ANGULAR ±3 °		MATERIAL NO.		SEE TABLE		SHEET NO. 1 OF 2				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



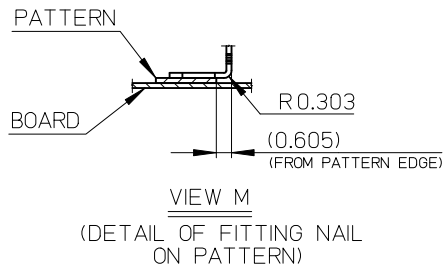
適合金めっきFPC推奨寸法
 APPLICABLE FPC OF GOLD
 PLATING RECOMMENDED DIMENSION
 仕上がり厚さ: 0.3±0.03
 THICKNESS: 0.3+0.03/-0.03



適合金めっきFFC推奨寸法
 APPLICABLE FFC OF GOLD
 PLATING RECOMMENDED DIMENSION
 仕上がり厚さ: 0.3±0.03
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参考基板レイアウト
 (マウント面)
 RECOMMENDED P.C BOARD
 PATTERN DIMENSION(REF.)
 (MOUNTING SIDE)



注記NOTES

1. 使用材料

MATERIAL

- ハウジング: 46ナイロン、ガラス充填、UL94V-0、白
- HOUSING: PA46, GLASS FILLED, UL94V-0, WHITE
- アクチュエータ: ポリフェニレンサルファイド (PPS)、ガラス充填、UL94V-0、黒
- ACTUATOR: POLYPHENYLENE SULFIDE, GLASS FILLED, UL94V-0, BLACK
- ターミナル: リン青銅、ニッケル下地金めっき (t=0.2)
- TERMINAL: PHOSPHOR BRONZE, GOLD OVER NICKEL PLATING
- 金具: リン青銅、ニッケル下地金めっき (t=0.2)
- FITTING NAIL: PHOSPHOR BRONZE, TIN OVER NICKEL PLATING

2. エンボステープ梱包時は、アクチュエータがロックした状態になります。

IN THE PACKAGE, ACTUATOR OF PART NO.52745-**59 SHOULD BE LOCKED.

3. ソルダテール半田付け面のズレ量、及び金具半田付け面のズレ量は、

基準面Hに対して上方向に0.1MAXIMUM、下方向0.15MAXIMUMとする。

MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM DATUM-H.

UPPER DIRECTION: 0.1MAXIMUM

LOWER DIRECTION: 0.15 MAXIMUM

4. 偶数極に適用

APPLY FOR EVEN CIRCUIT.

5. ハターン剥離止め金具

FITTING NAIL FOR PREVENTION OF PEELING OF P.W.B. PATTERN.

6. R0.3は、FPCの胴体部にかからないこと

R0.3 MUST NOT BE OVERLAPED TO PATTERN OF FPC.

7. ELV 及び RoHS 適合品

ELV AND RoHS COMPLIANT

FPCについて:

打抜き方向は導体側から補強板を推奨致します。
 補強フィルム材質はポリイミドを推奨致します。
 接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:

RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.

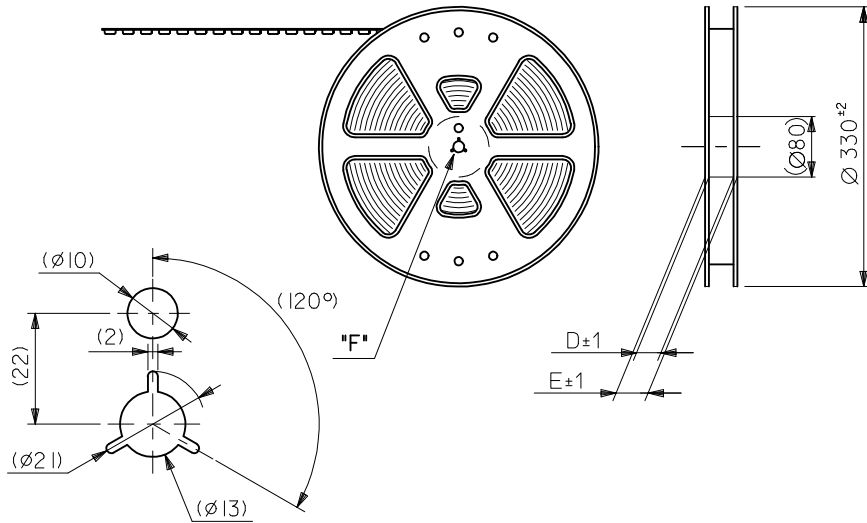
RECOMMENDED MATERIAL :

STIFFENER FILM : POLYIMIDE

BONDING AGENT : THERMOSETTING BONDING AGENT

REVISED EC NO: J2011-0041 DRWN: HYOSHINO 2010/07/08 CHKD: SHIMOMIYAMA 2010/07/08 APPR: KMORIKAWA 2010/07/16	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION		
				MM ONLY		5:1	METRIC	◎ □		
		10 UNDER	± ---	DRAWN BY	DATE	TITLE				
		10 OVER 30 UNDER	± ---	M. NABE I	'05/02/14	0.5 FPC CONN. ZIF FOR SMT R/A (UPPER CONTACT) GOLD PLATING				
30 OVER	± ---	CHECKED BY	DATE							
		ANGULAR ± --- °		APPROVED BY		DATE	MOLEX INCORPORATED			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		N. UKITA		'05/02/14	MOLEX INCORPORATED			
				MATERIAL NO.		DOCUMENT NO.	SHEET NO.			
				SEE TABLE		SD-52745-050	2 OF 2			
				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

引き出し方向
←
PULL OUT
DIRECTION



DETAIL "F"

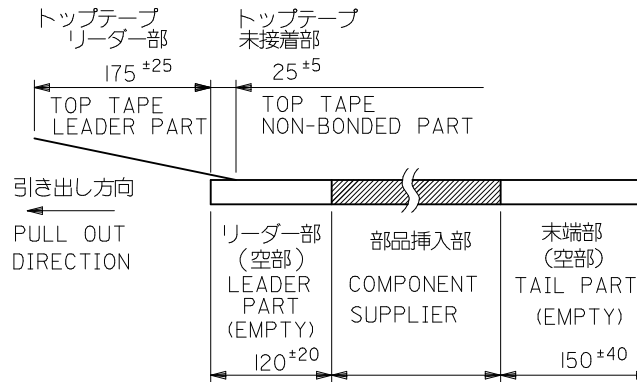
5. 材料 キャリアテープ:ポリプロピレン (PP)
 トップテープ:PET, PE, PEF
 リール:ポリスチレン (PS) <リサイクル材を含む>
 MATERIAL CARRIER TAPE:POLYPROPYLENE
 TOP TAPE:PET,PE,PEF
 REEL:POLYSTYRENE(PS)
 <RECYCLE MATERIAL CONTAINED>

6. 本製品は 52745- **90 の鉛フリー品である。
 THIS PRODUCT IS LEAD FREE OF 52745-**90

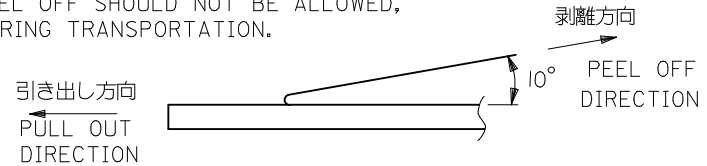
7. 本製品は乾燥剤入り、ハイバリア梱包仕様である。
 THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

注記 NOTES

- 製品番号 52745-**59 の梱包状態はアクチュエータがロックした状態とする。
 詳細寸法については図面 SD-52745-050 を参照下さい。
 IN THE PACKAGE,ACTUATOR OF PART NO.52745-**59 SHOULD BE LOCKED RE DETAILED DIMENSIONS,SEE SD-52745-050.
- 梱包数量:1000個/リール
 NUMBER OF CONNECTORS:1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH

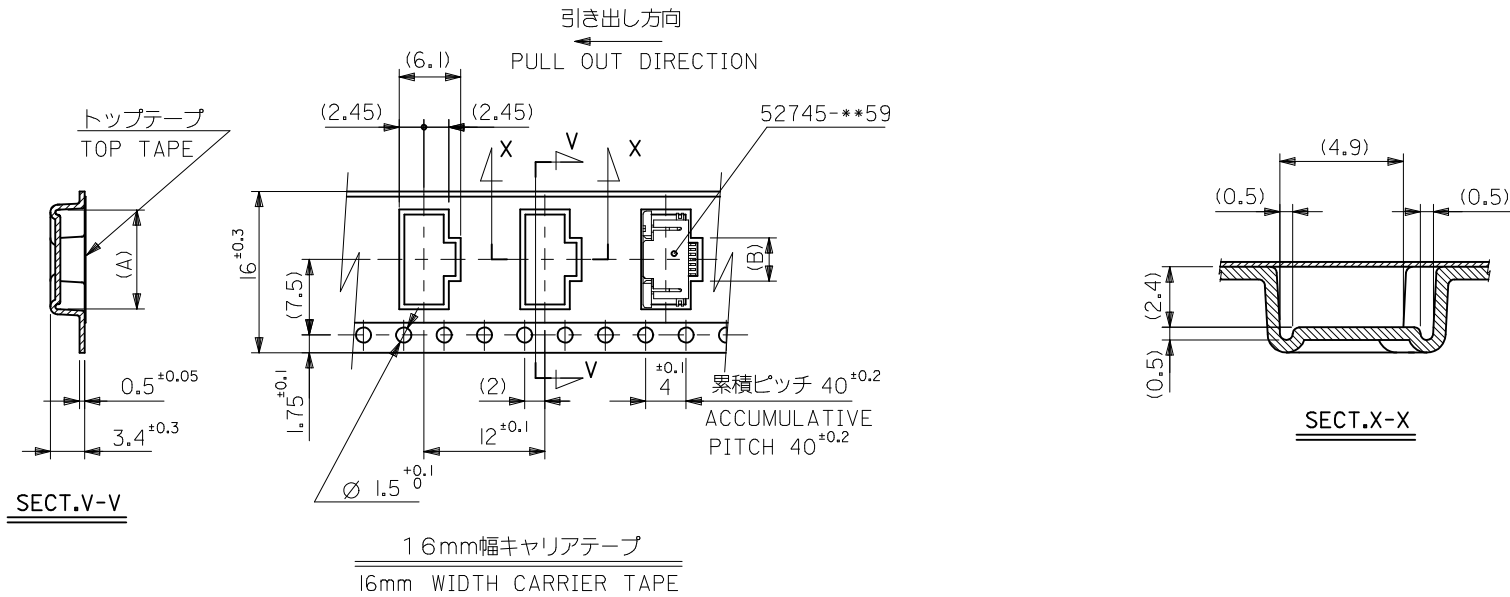


- トップテープの剥離強度:(剥離方向は下図参照)
 0.1N~1.3N(10gf~130gf)尚、本規格値は、出荷時に適用。
 (但し、輸送時に剥離が発生しない事。)
 PEELING OFF FORCE OF TOP TAPE:
 0.1N~1.3N(10gf~130gf)(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
 THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT
 PEEL OFF SHOULD NOT BE ALLOWED,
 DURING TRANSPORTATION.



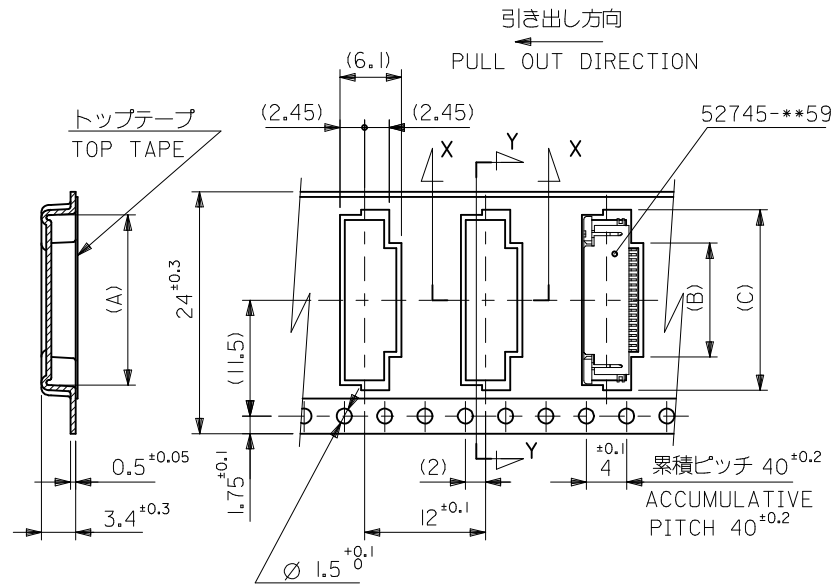
52745-**97 MODEL NO.

REVISED EC NO: J2009-2061 DRWN:TKON 2009/05/20 CHKD:HMATSUMOTO 2009/05/21 APPR:NUKITA 2009/05/21	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
	10 UNDER	±---	DRAWN BY M.NABEI	DATE '05/02/14	TITLE 0.5 FPC CONN UPR CONT EMBSTP PKG -LEAD FREE-				
	10 OVER 30 UNDER	±---	CHECKED BY K.TOJO	DATE '05/02/14	MOLEX INCORPORATED				
	30 OVER	±---	APPROVED BY N.NUKITA	DATE '05/02/14	DOCUMENT NO. SD-52745-051		SHEET NO. 1 OF 3		
REV	DESCRIPTION	ANGULAR ±---°	MATERIAL NO. SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3					



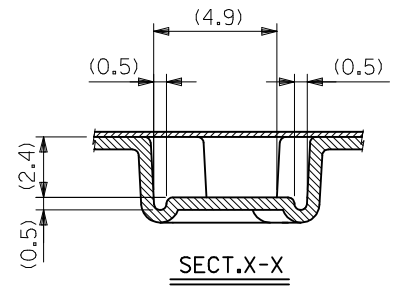
16	21.4	17.4	2.8	8.4	52745-0497	4
キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(B)	(A)	MATERIAL NO.	極数 CIRCUIT

REVISED EC NO.: J2009-2061 DRWN:TKGN 2009/05/20 CHKD:HMATSUMOTO 2009/05/21 APPR:NUKITA 2009/05/21	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	REV	10 UNDER ±---	DRAWN BY M. NABEI	DATE '05/02/14	TITLE 0.5 FPC CONN UPR CONT EMBSTP PKG -LEAD FREE-	
		10 OVER 30 UNDER ±---	CHECKED BY K. TOJO	DATE '05/02/14	APPROVED BY N. UKITA	
		30 OVER ±---	DATE '05/02/14	MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-52745-051
		ANGULAR ±--- °	MOLEX INCORPORATED			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



SECT.Y-Y

24mm幅キャリアテープ
24mm WIDTH CARRIER TAPE



24	29.4	25.4	17.4	10.8	16.4	52745-2097	20
			16.9	10.3	15.9	-1997	19
			16.4	9.8	15.4	-1897	18
			15.9	9.3	14.9	-1797	17
			15.4	8.8	14.4	-1697	16
			14.9	8.3	13.9	-1597	15
			14.4	7.8	13.4	-1497	14
			13.9	7.3	12.9	-1397	13
			13.4	6.8	12.4	-1297	12
			12.9	6.3	11.9	-1197	11
			12.4	5.8	11.4	-1097	10
			11.9	5.3	10.9	-0997	9
			11.4	4.8	10.4	-0897	8
10.9	4.3	9.9	-0797	7			
10.4	3.8	9.4	52745-0697	6			
キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(C)	(B)	(A)	MATERIAL NO.	極数 CIRCUIT

REVISED EC NO: J2009-2061 DRWN:TKON 2009/05/20 CHKD:HMATSUMOTO 2009/05/21 APPR:NUKITA 2009/05/21	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY M. NABEI	DATE '05/02/14	TITLE 0.5 FPC CONN UPR CONT EMBSTP PKG -LEAD FREE-			
	10 OVER 30 UNDER	± ---	CHECKED BY K. TOJO	DATE '05/02/14	MOLEX INCORPORATED			
	30 OVER	± ---	APPROVED BY N. UKITA	DATE '05/02/14	DOCUMENT NO. SD-52745-051		SHEET NO. 3 OF 3	
	ANGULAR ± --- °		MATERIAL NO. SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS								